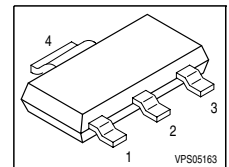


**Cool MOS™ Power Transistor**
**Feature**

- New revolutionary high voltage technology
- Ultra low gate charge
- Extreme  $dv/dt$  rated
- Ultra low effective capacitances
- Improved transconductance
- Qualified according to JEDEC<sup>0)</sup> for target applications

$V_{DS} @ T_{jmax}$	650	V
$R_{DS(on)}$	6	$\Omega$
$I_D$	0.3	A

SOT-223



Type	Package	Ordering Code	Marking
SPN01N60C3	SOT-223	Q67040-S4208	01N60C3

drain pins 2, 4


 gate pin 1  
source pin3

**Maximum Ratings**

Parameter	Symbol	Value	Unit
Continuous drain current $T_A = 25\text{ °C}$ $T_A = 70\text{ °C}$	$I_D$	0.3 0.2	A
Pulsed drain current, $t_p$ limited by $T_{jmax}$ $T_A = 25\text{ °C}$	$I_D \text{ puls}$	1.6	
Gate source voltage static	$V_{GS}$	$\pm 20$	V
Gate source voltage AC ( $f > 1\text{Hz}$ )	$V_{GS}$	$\pm 30$	
Power dissipation, $T_A = 25\text{ °C}$	$P_{tot}$	1.8	W
Operating and storage temperature	$T_j, T_{stg}$	-55... +150	$^{\circ}\text{C}$

**Maximum Ratings**

Parameter	Symbol	Value	Unit
Drain Source voltage slope $V_{DS} = 480\text{ V}$ , $I_D = 0.8\text{ A}$ , $T_j = 125\text{ °C}$	$dv/dt$	50	V/ns

**Thermal Characteristics**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Thermal resistance, junction - soldering point	$R_{thJS}$	-	35	-	K/W
SMD version, device on PCB: @ min. footprint @ 6 cm <sup>2</sup> cooling area <sup>1)</sup>	$R_{thJA}$	-	110	75	
		-	-	72	
Soldering temperature, 1.6 mm (0.063 in.) from case for 10s	$T_{sold}$	-	-	260	°C

**Electrical Characteristics, at  $T_j=25\text{ °C}$  unless otherwise specified**

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}$ , $I_D=0.25\text{mA}$	600	-	-	V
Drain-Source avalanche breakdown voltage	$V_{(BR)DS}$	$V_{GS}=0\text{V}$ , $I_D=0.8\text{A}$	-	700	-	μA
Gate threshold voltage	$V_{GS(th)}$	$I_D=250\text{μA}$ , $V_{GS}=V_{DS}$	2.3	3	3.7	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=600\text{V}$ , $V_{GS}=0\text{V}$ , $T_j=25\text{ °C}$ , $T_j=150\text{ °C}$	-	0.5	1	
Gate-source leakage current	$I_{GSS}$	$V_{GS}=30\text{V}$ , $V_{DS}=0\text{V}$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}$ , $I_D=0.5\text{A}$ , $T_j=25\text{ °C}$ $T_j=150\text{ °C}$	-	5.5	6	Ω
			-	15.1	-	

**Electrical Characteristics** , at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Transconductance	$g_{fs}$	$V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$ , $I_D = 0.2\text{A}$	-	0.45	-	S
Input capacitance	$C_{iss}$	$V_{GS} = 0\text{V}$ , $V_{DS} = 25\text{V}$ , $f = 1\text{MHz}$	-	100	-	pF
Output capacitance	$C_{oss}$		-	40	-	
Reverse transfer capacitance	$C_{rss}$		-	2.5	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 350\text{V}$ , $V_{GS} = 0/10\text{V}$ , $I_D = 0.3\text{A}$ , $R_G = 100\Omega$	-	45	-	ns
Rise time	$t_r$		-	30	-	
Turn-off delay time	$t_{d(off)}$		-	60	90	
Fall time	$t_f$		-	30	45	

**Gate Charge Characteristics**

Gate to source charge	$Q_{gs}$	$V_{DD} = 350\text{V}$ , $I_D = 0.3\text{A}$	-	0.9	-	nC
Gate to drain charge	$Q_{gd}$		-	2.2	-	
Gate charge total	$Q_g$	$V_{DD} = 350\text{V}$ , $I_D = 0.3\text{A}$ , $V_{GS} = 0\text{ to }10\text{V}$	-	3.9	5	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 350\text{V}$ , $I_D = 0.3\text{A}$	-	5.5	-	V

<sup>0</sup>J-STD20 and JESD22

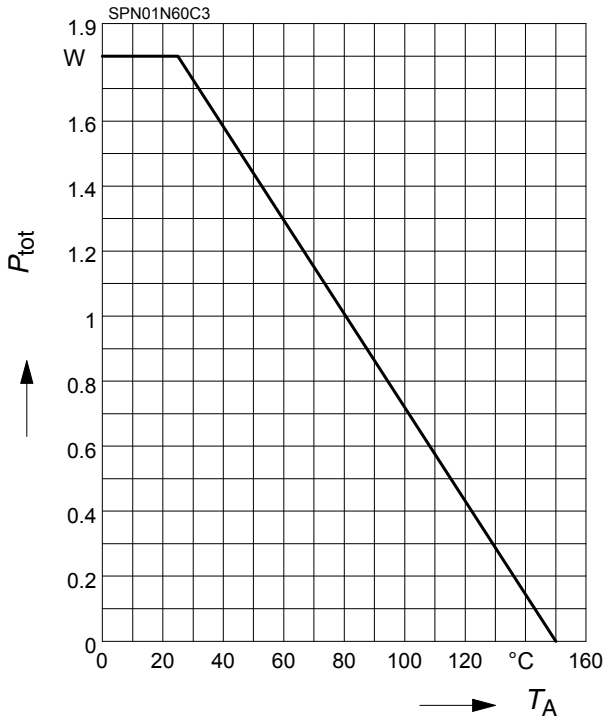
<sup>1</sup>Device on 40mm\*40mm\*1.5mm epoxy PCB FR4 with 6cm<sup>2</sup> (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.

**Electrical Characteristics, at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Inverse diode continuous forward current	$I_S$	$T_A=25^\circ\text{C}$	-	-	0.3	A
Inverse diode direct current, pulsed	$I_{SM}$		-	-	1.6	
Inverse diode forward voltage	$V_{SD}$	$V_{GS}=0\text{V}, I_F=I_S$	-	0.85	1.05	V
Reverse recovery time	$t_{rr}$	$V_R=350\text{V}, I_F=I_S,$	-	200	340	ns
Reverse recovery charge	$Q_{rr}$	$di_F/dt=100\text{A}/\mu\text{s}$	-	0.45	-	$\mu\text{C}$

**1 Power dissipation**

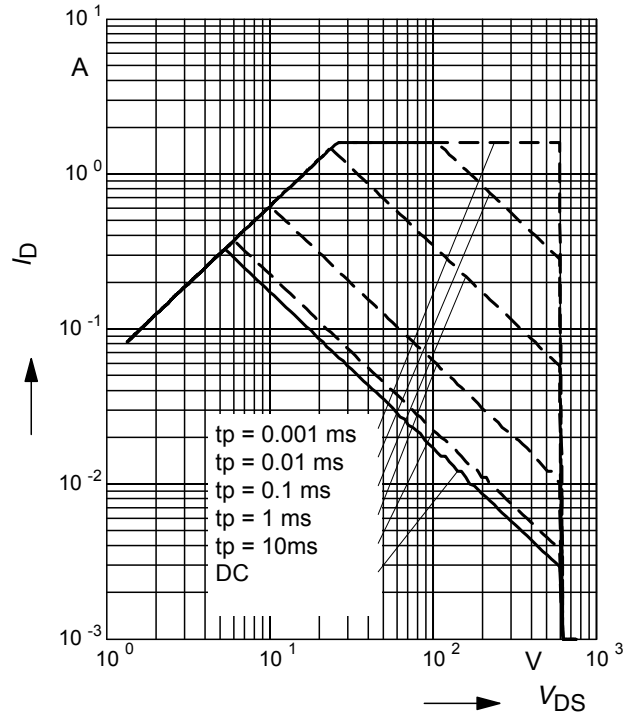
$P_{tot} = f(T_A)$



**2 Safe operating area**

$I_D = f(V_{DS})$

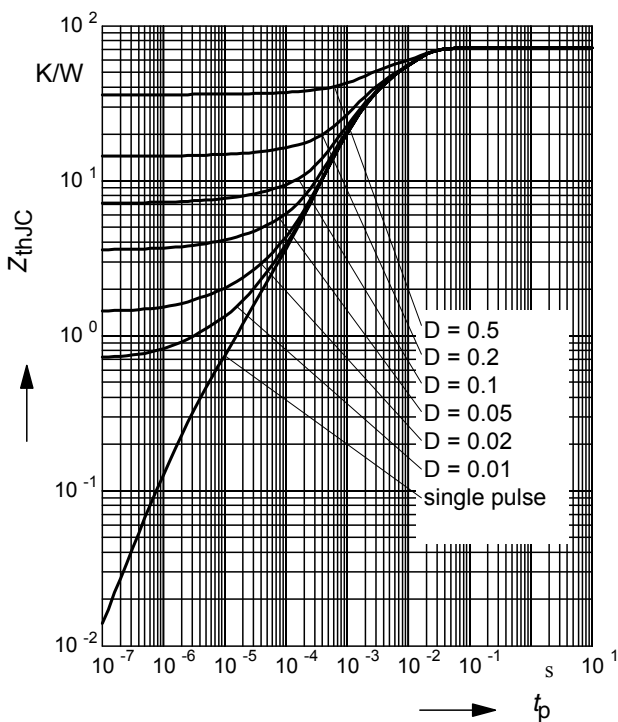
parameter :  $D = 0$  ,  $T_A = 25^\circ C$



**3 Transient thermal impedance**

$Z_{thJC} = f(t_p)$

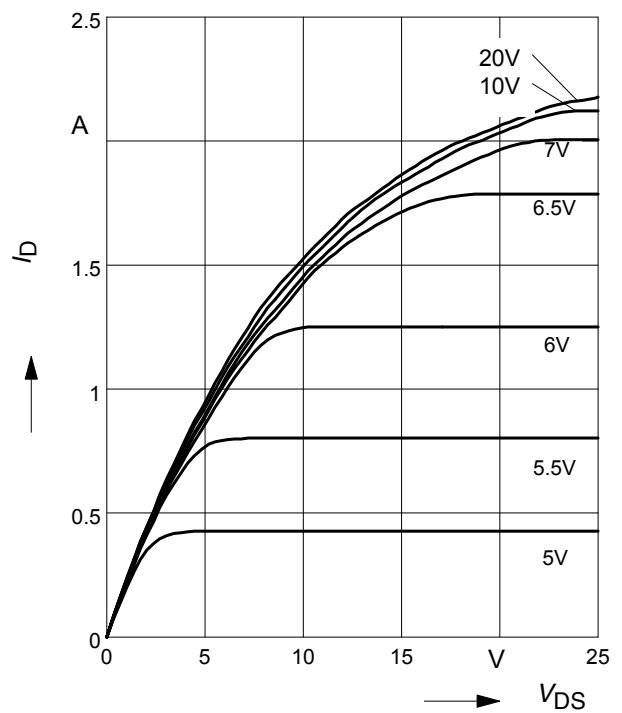
parameter:  $D = t_p/T$



**4 Typ. output characteristic**

$I_D = f(V_{DS})$ ;  $T_j = 25^\circ C$

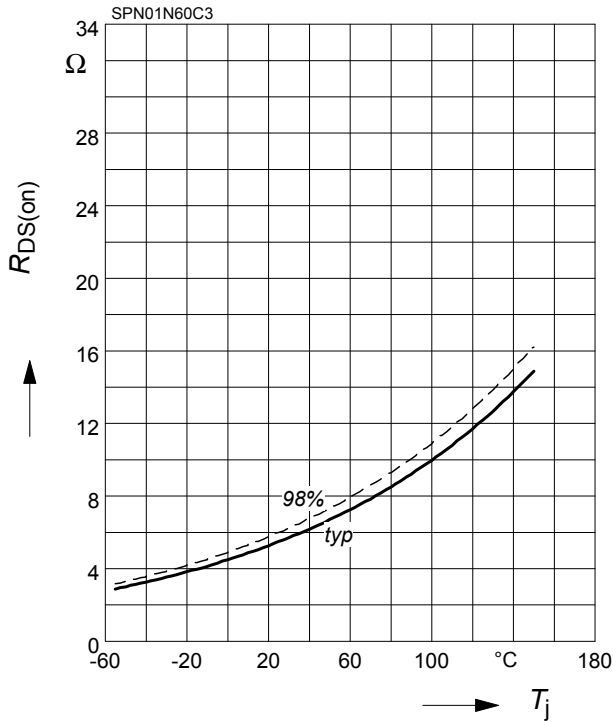
parameter:  $t_p = 10 \mu s$ ,  $V_{GS}$



**5 Drain-source on-state resistance**

$$R_{DS(on)} = f(T_j)$$

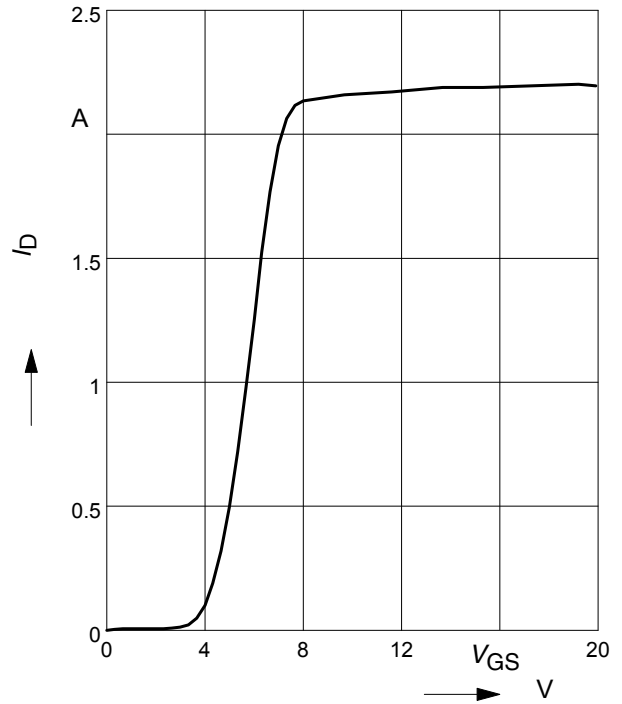
parameter:  $I_D = 0.2 \text{ A}$ ,  $V_{GS} = 10 \text{ V}$



**6 Typ. transfer characteristics**

$$I_D = f(V_{GS}); V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$$

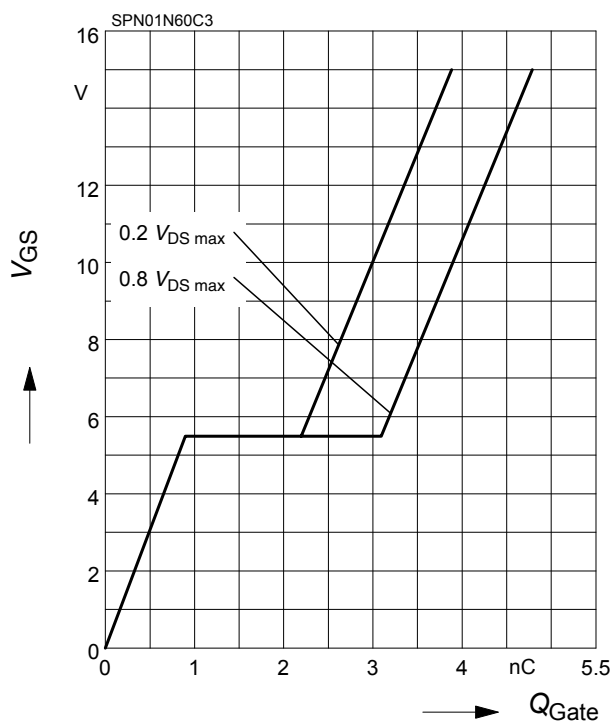
parameter:  $t_p = 10 \mu\text{s}$



**7 Typ. gate charge**

$$V_{GS} = f(Q_{Gate})$$

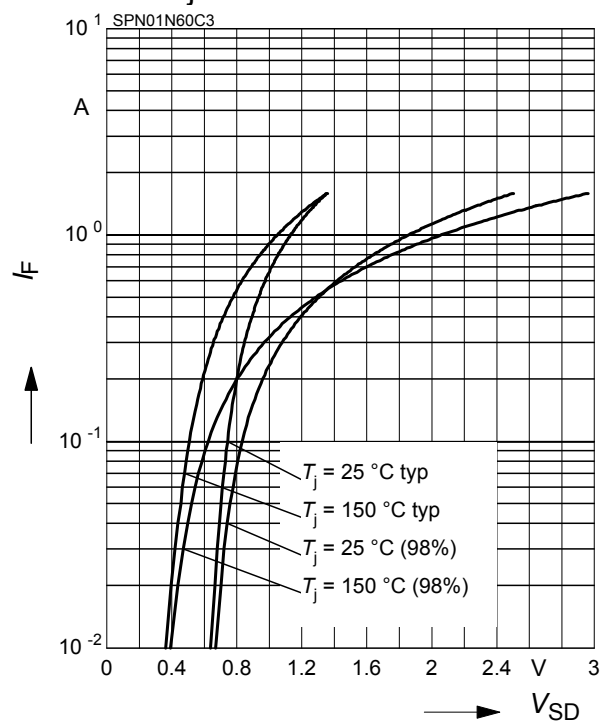
parameter:  $I_D = 0.3 \text{ A}$  pulsed



**8 Forward characteristics of body diode**

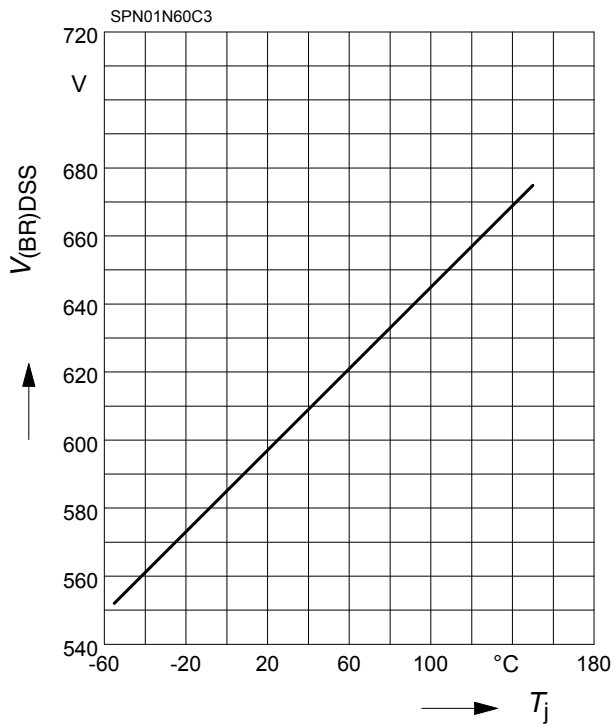
$$I_F = f(V_{SD})$$

parameter:  $T_j$ ,  $t_p = 10 \mu\text{s}$



### 9 Drain-source breakdown voltage

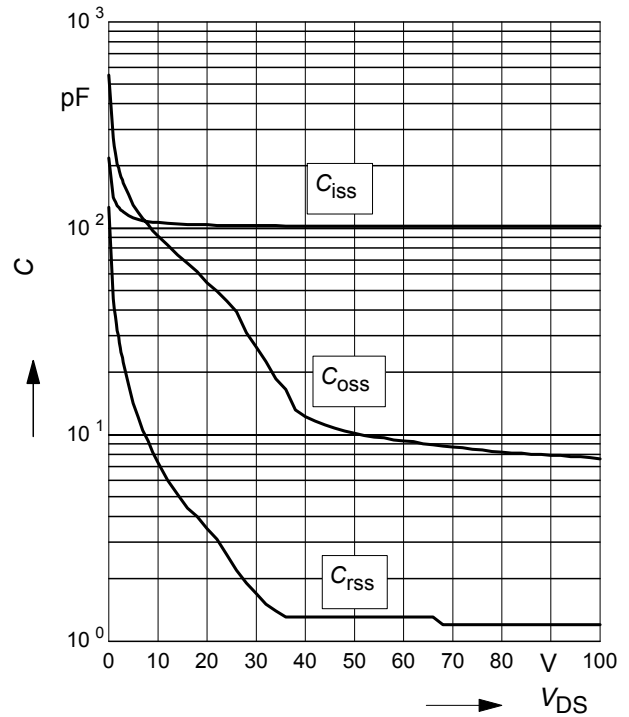
$$V_{(BR)DSS} = f(T_j)$$



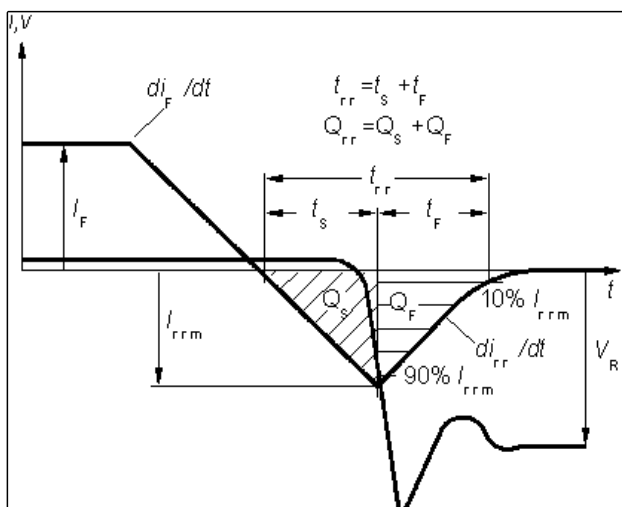
### 10 Typ. capacitances

$$C = f(V_{DS})$$

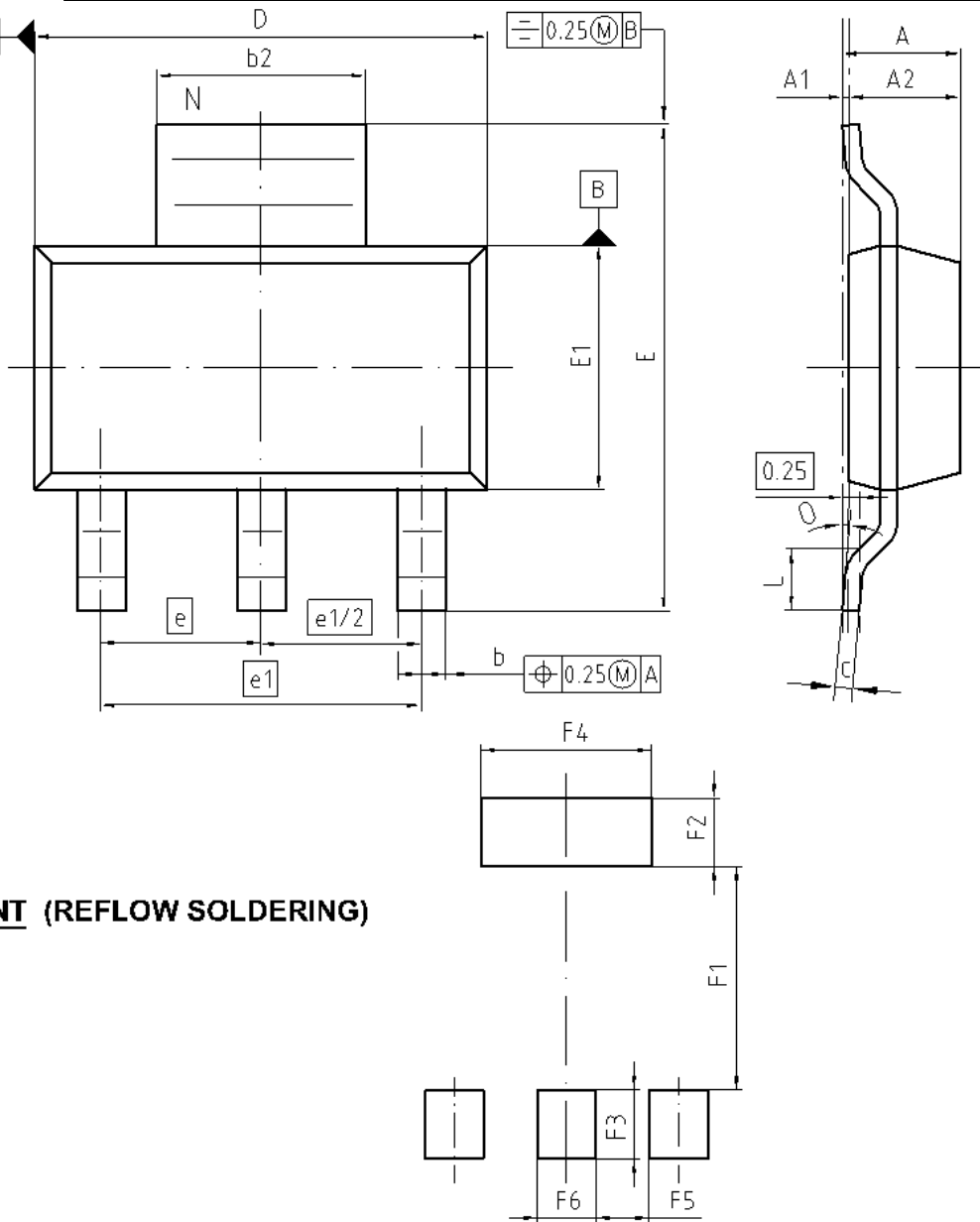
parameter:  $V_{GS}=0V, f=1\text{ MHz}$



### Definition of diodes switching characteristics



SOT-223



**FOOTPRINT (REFLOW SOLDERING)**

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.6	1.8	0.063	0.071
A1	-	0.1	-	0.004
A2	1.5	1.7	0.059	0.067
b	0.6	0.8	0.024	0.031
b2	2.9	3.1	0.114	0.122
c	0.24	0.32	0.009	0.013
D	6.3	6.7	0.248	0.264
E	6.7	7.3	0.264	0.287
E1	3.3	3.7	0.123	0.146
e	2.3 BASIC		0.091 BASIC	
e1	4.6 BASIC		0.181 BASIC	
L	0.75	-	0.023	-
N	4		4	
O	0°	10°	0°	10°
F1	1.8 BASIC		0.189 BASIC	
F2	1.4 BASIC		0.055 BASIC	
F3	1.4 BASIC		0.055 BASIC	
F4	3.5 BASIC		0.138 BASIC	
F5	1.1 BASIC		0.043 BASIC	
F6	1.2 BASIC		0.047 BASIC	

**REFERENCE**  
JEDEC TO261 AA

**SCALE**

**EUROPEAN PROJECTION**

**ISSUE DATE**  
04-28-2006

**FILE**  
SOT223



**Published by**  
**Infineon Technologies AG,**  
**81726 Munich, Germany**

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